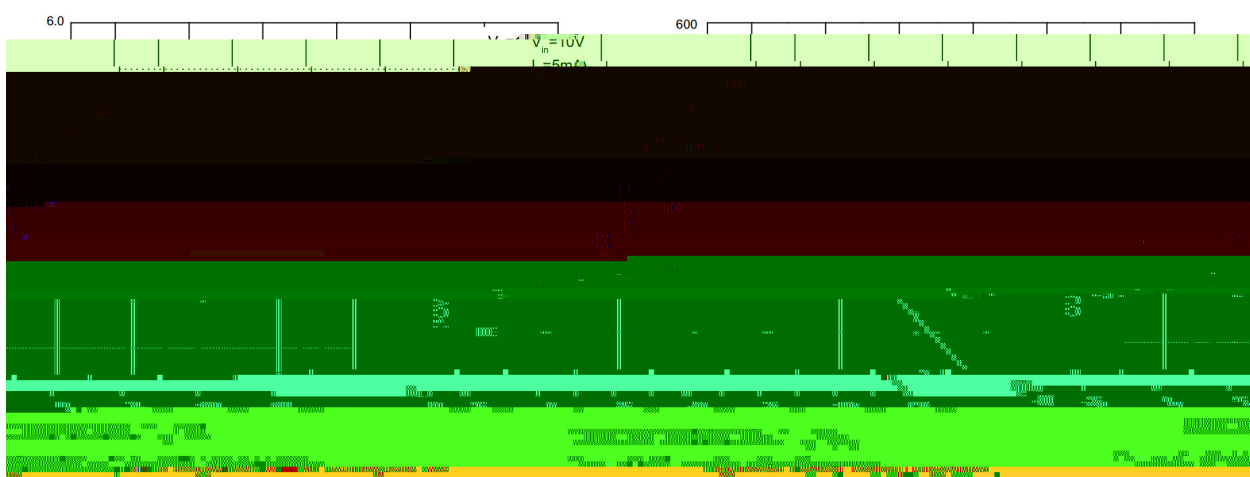
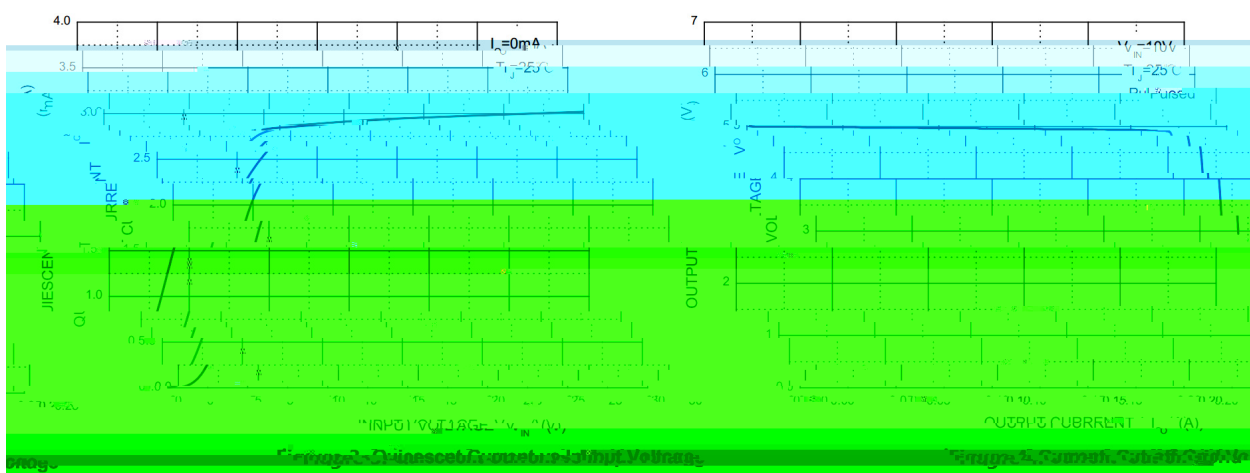
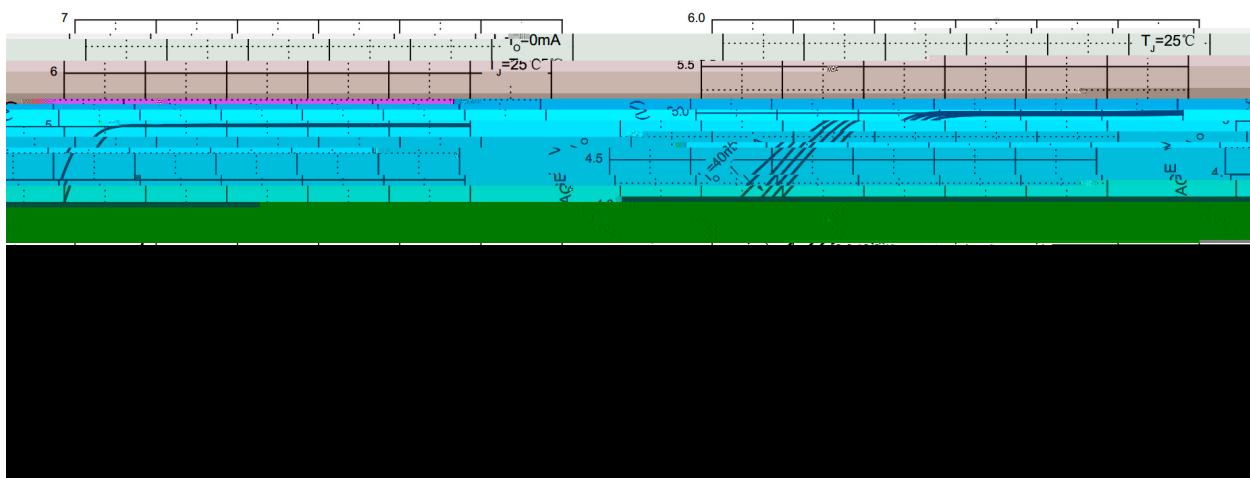


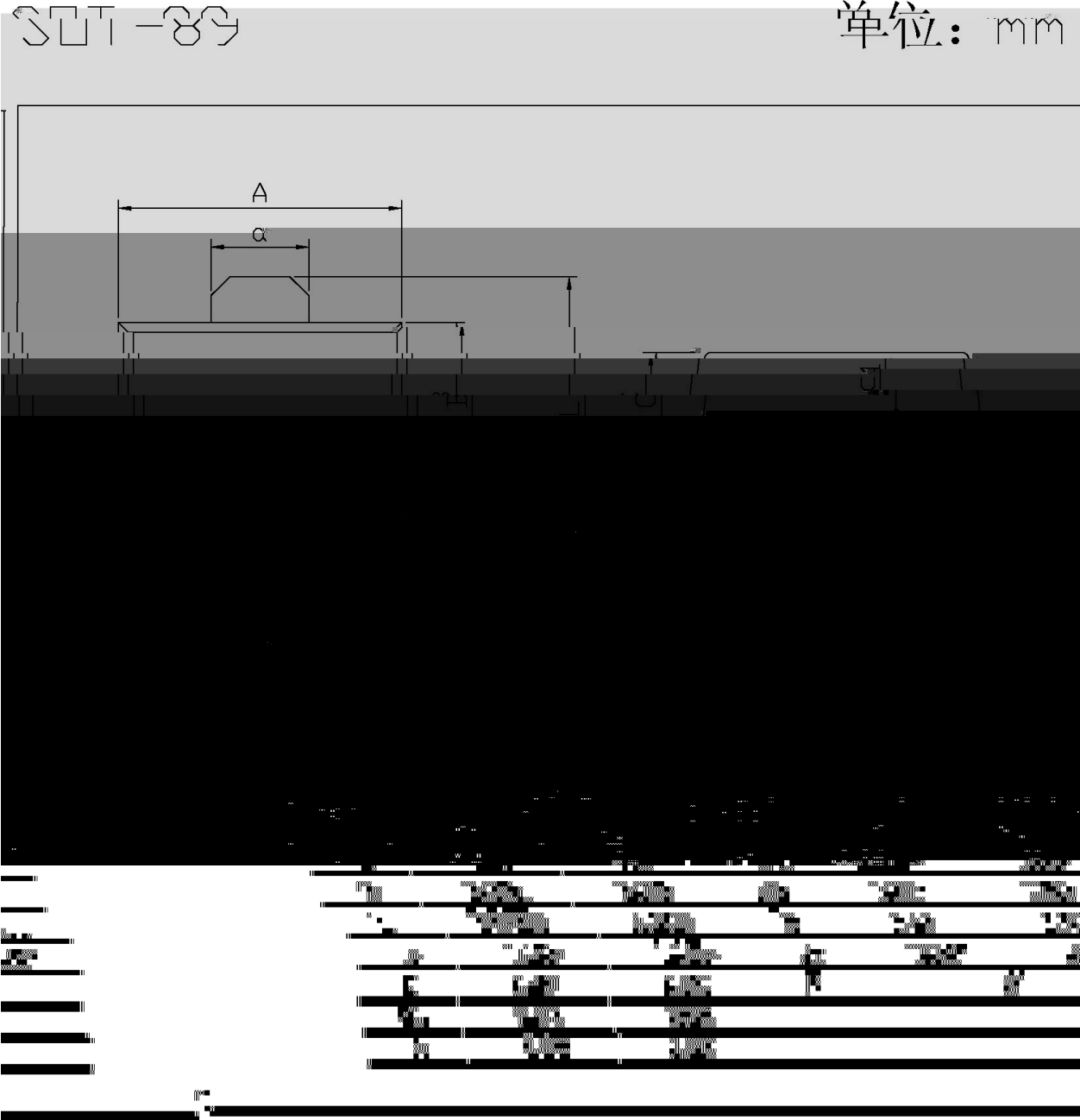
Parameter	Symbol	Rating	Unit
Input voltage	V_I	36	V
Output current($V_I=8V$)	I_O	100	mA
Operating virtual Junction temperature	T_J	0 125	
Power Dissipation	P_D	500	mW
Storage temperature range	T_{stg}	-65 150	
Thermal resistance junction-ambient	R_{JA}	200	/W

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Output voltage	V_O	$I_O = 40mA$ $T_J=25$	4.80	5.0	5.2	V
		$I_O=1mA$ to 40mA $V_I=7V$ to 20V	4.75	5.0	5.25	V
		$I_O=1mA$ to 70mA $V_I=10V$	4.75	5.0	5.25	V
Input regulation	V_O	$V_I=7V$ to 20V $T_J=25$		32	150	mV

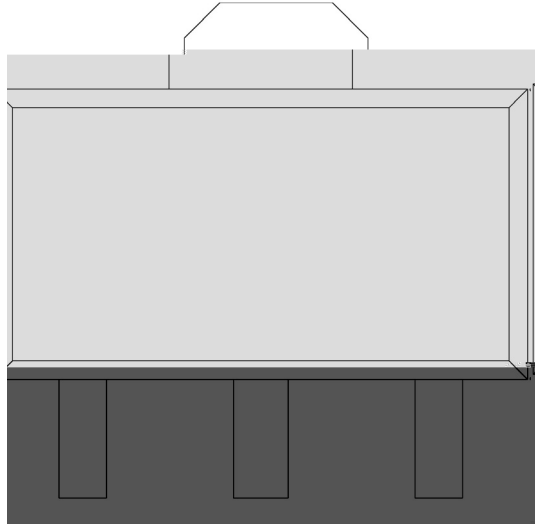
/ Electrical Characteristic Curve



/ Package Dimensions



/ Marking Instructions



H
L05

() / Temperature Profile for IR Reflow Soldering(Pb-Free)

- Note:

1

150 180

60 90sec;

1.Preheating:150~180 , Time:60~90sec.

2

245±5

5±0.5sec;

2.Peak Temp.:245±5 , Duration:5±0.5sec.

3

2 10 /sec.

3. Cooling Speed: 2~10 /sec.

/ Resistance to Soldering Heat Test Conditions

260±5 10±1 sec. Temp.:260±5 Time:10±1 sec

/ REEL

Package Type	Units	Dimension	(unit mm ³)
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